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Dimensions

Chip Size	1812
L	4.52mm +/-0.3mm (0.178 in +/-0.012 in)
W	3.2mm +/-0.3mm (0.126 in +/-0.012 in)
T	2.79mm MAX (0.11 in MAX)
B	0.61mm +/-0.46mm (0.024 in +/-0.018 in)

Packaging Specifications

Packaging	T&R
Packaging Quantity	1000

General Information

Series	SMD MIL COG PRF32535
Style	SMD Chip
Description	SMD, Low ESR, MIL-PRF-32535
RoHS	Yes
Termination	Flexible Termination
Failure Rate	N/A
Qualifications	MIL-PRF-32535 M-Level
AEC-Q200	No
Shelf Life	78 Weeks
MSL	1

Specifications

Capacitance	3900 pF
Capacitance Tolerance	10%
Voltage DC	200 VDC
Dielectric Withstanding Voltage	500 VDC
Temperature Range	-55/+125°C
Temperature Coefficient	COG
Dissipation Factor	0.15% 1 MHz 25C
Aging Rate	0% Loss/Decade Hour
Insulation Resistance	100 GOhms

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